

Mechanisms of bubble growth and blistering on metals exposed to hydrogen

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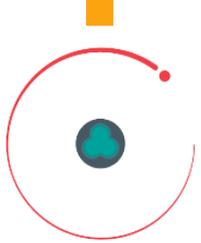
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Outline



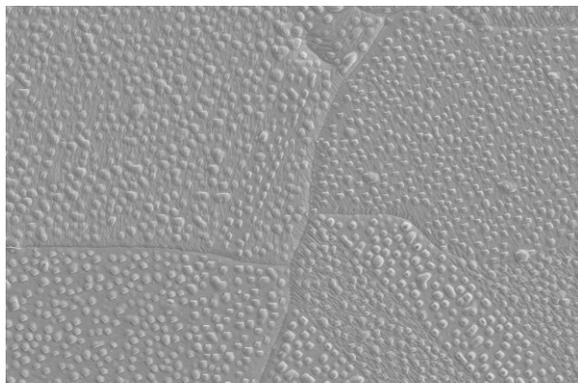
- Introduction & Motivation:
 - Dislocations, hydrogen and surface behavior.
- Effect on surfaces (MD). Influence of grain orientation at low fluences
- Cu-H machine-learned interatomic potential
- Conclusions



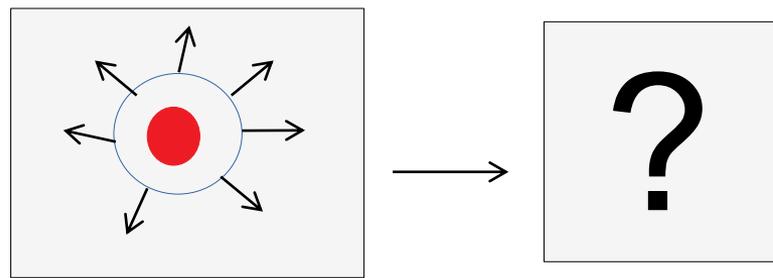
Motivation



- Cu is the first candidate for particle accelerators in the field of high energy physics
 - High thermal and electric conductivity as well as ductility properties make Cu superior to many other metals
 - It is widely used in accelerating structures such as CLIC and RFQ structures for proton linac injectors
- H tends to penetrate Cu and accumulates in some voids close to the surface, when relatively low energy H^- (~ 45 keV) is used in accelerator



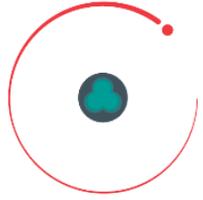
10 μ m
EHT = 10.00 kV
WD = 7.9 mm
Signal A = SE2
Sample ID = Cu-OFE_after irr. test_
Date: 16 Oct 2020
Mag = 1.00 K X
EN



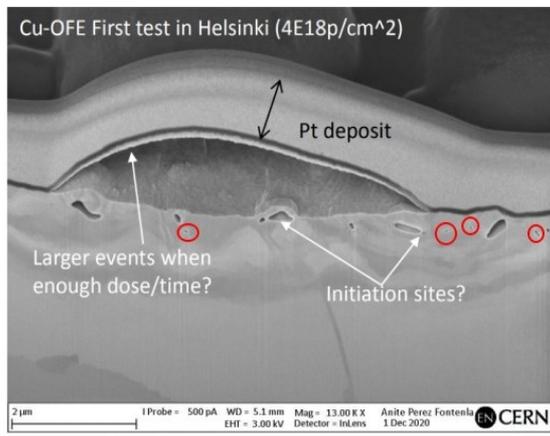
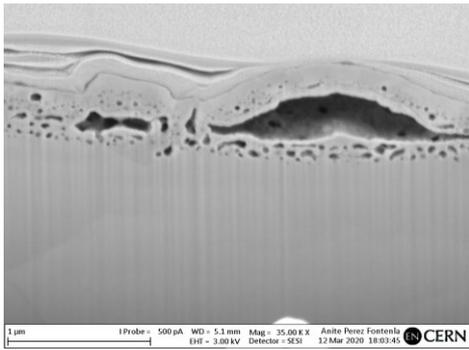
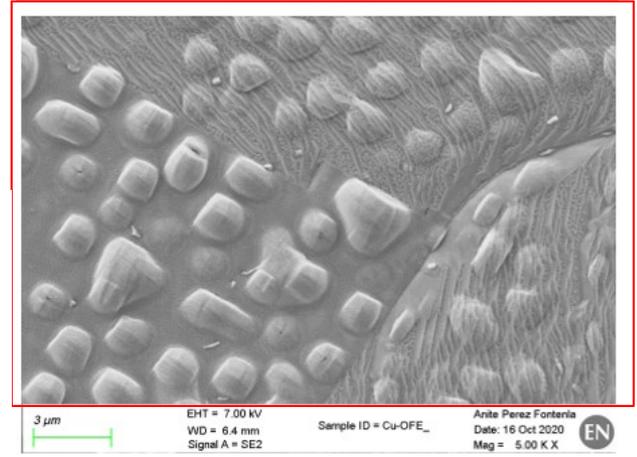
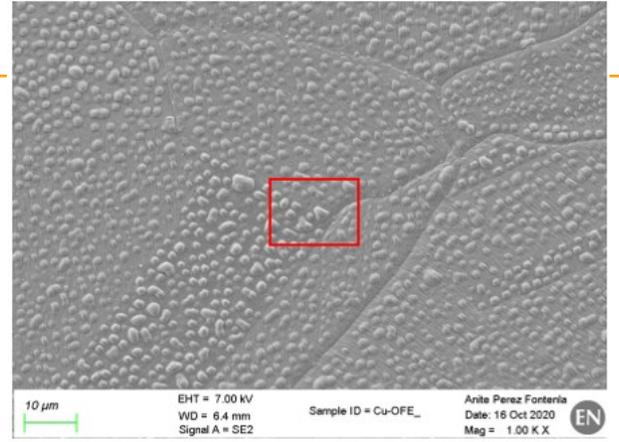
H gas bubble



Blister at Cu surfaces

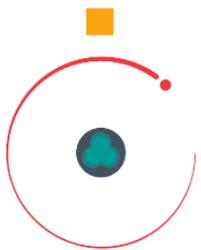


- Experimentally bubbles appear close to the surface seen in SEM images as protrusions or H blisters
- Also, protrusions that appear in the Cu surface are of different shapes

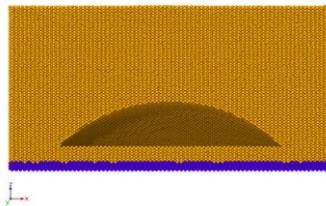
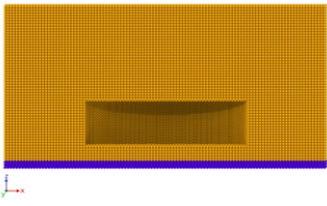
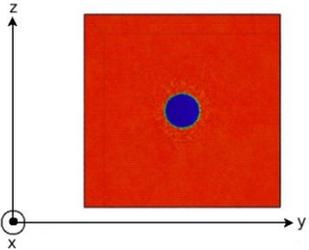




Simulation details



- We use molecular dynamics (MD) to study this effect. Mishin Embedded Atom Method (EAM) potential for Cu, EAM for H-H and **purely repulsive** H-Cu.
- MD is limited in the time and size of the cell, however, it provides a good description of the atomic interactions using interatomic potentials
- Problem of H accumulation and complete creation of defects is beyond the MD time span.
- Solution for H accumulation: introducing directly high concentrations (high pressures) of H ($n_{\text{H}/\text{Vac}}$: number of H per vacancy in the void), we can speed up the process.



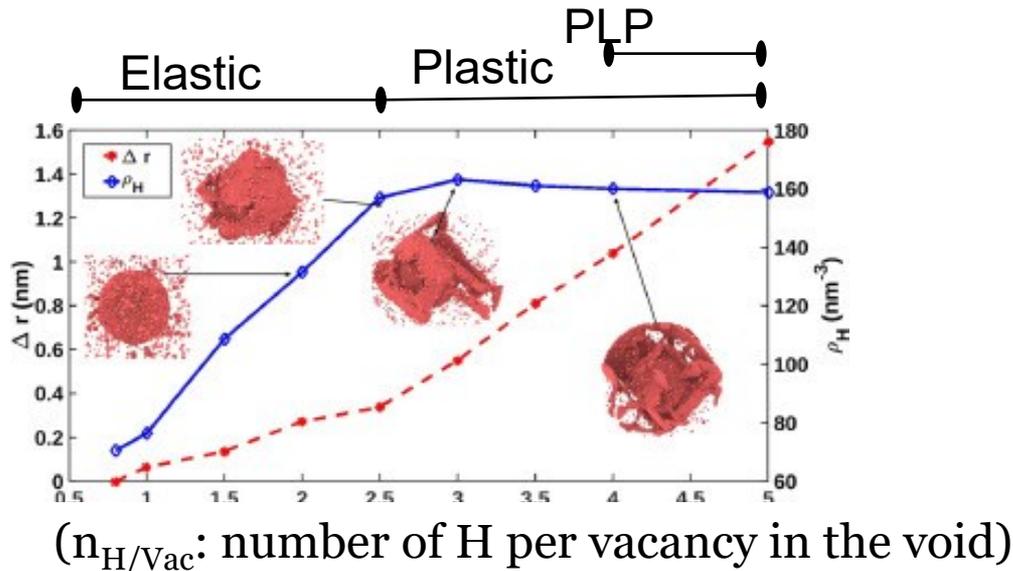
To enable large void simulations, we use different void shapes (sphere, hemisphere, disk) and surface orientations ($\{100\}$, $\{111\}$, $\{110\}$).

Bubble growth in Cu

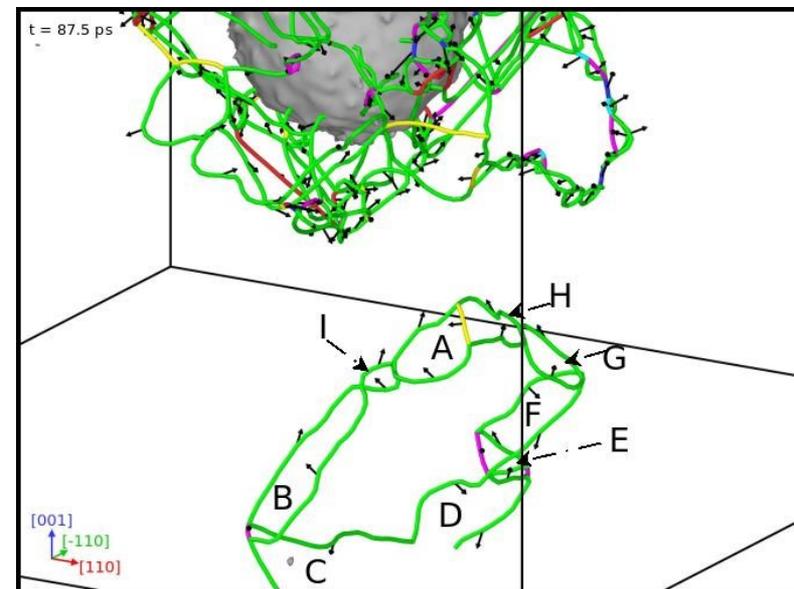
➤ To model this effect, some computational approaches have been implemented before with different outcomes.

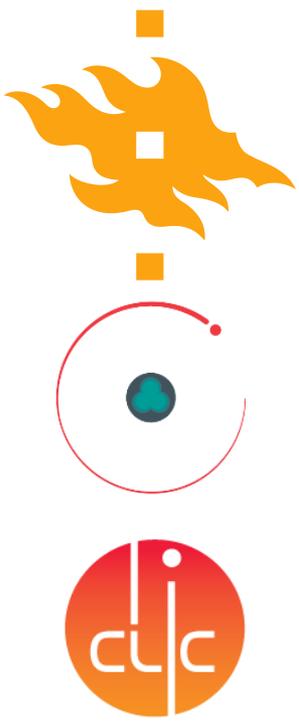
➤ The growth of tiny He bubble was followed in Cu, showing the dissociation of small prismatic loops [Jin et al., Sci. Rep. 11 (2021) 12839]

➤ We showed that even much larger bubbles grow via prismatic loop punching (PLP). In this case the network of shear loops is forming on adjacent $\{111\}$ planes with Burgers vector either aligned or opposite to the gliding direction of the prismatic loop [A. Lopez, F. Djurabekova et al. Acta Materialia 225 (2022) 117554]



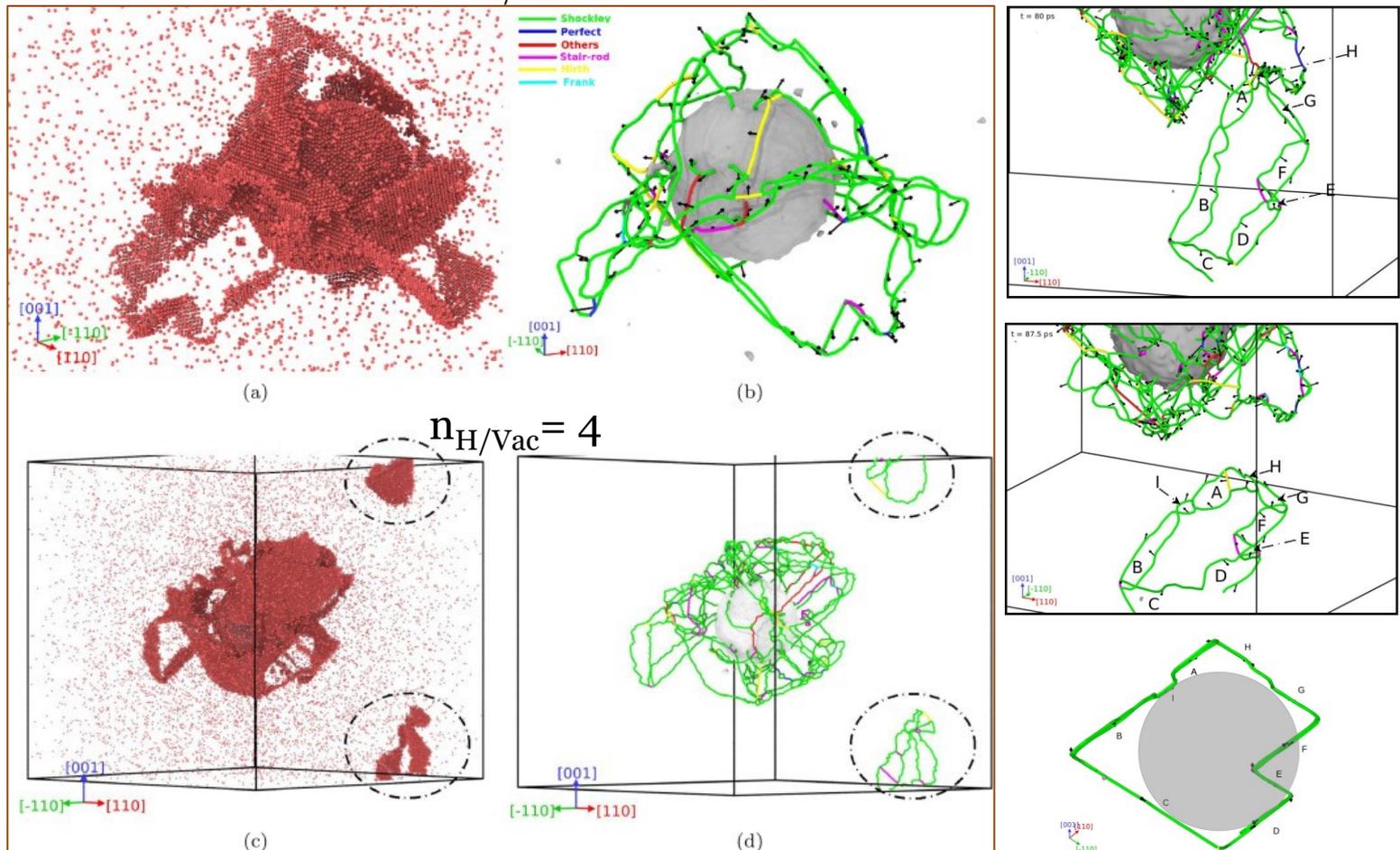
Alvaro Lopez Cazallia





Prismatic loop of arbitrary face in FCC lattice

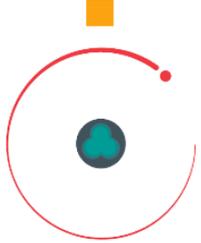
$$n_{H/Vac} = 3$$



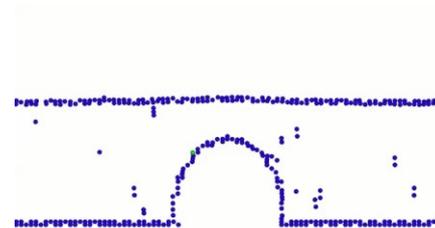
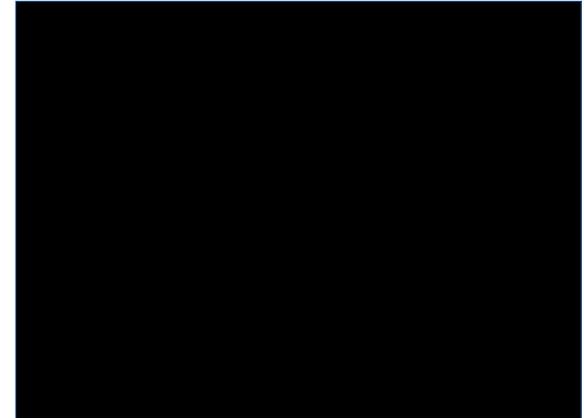
[A. Lopez, F.Djurabekova et al. Acta Materialia 225 (2022) 117554]



H bubble under the surface

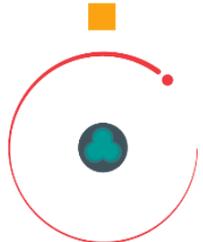


- Now we place the void near surface
- Loop punching proceeds via very similar mechanism, but the dislocation loops are attracted by surface

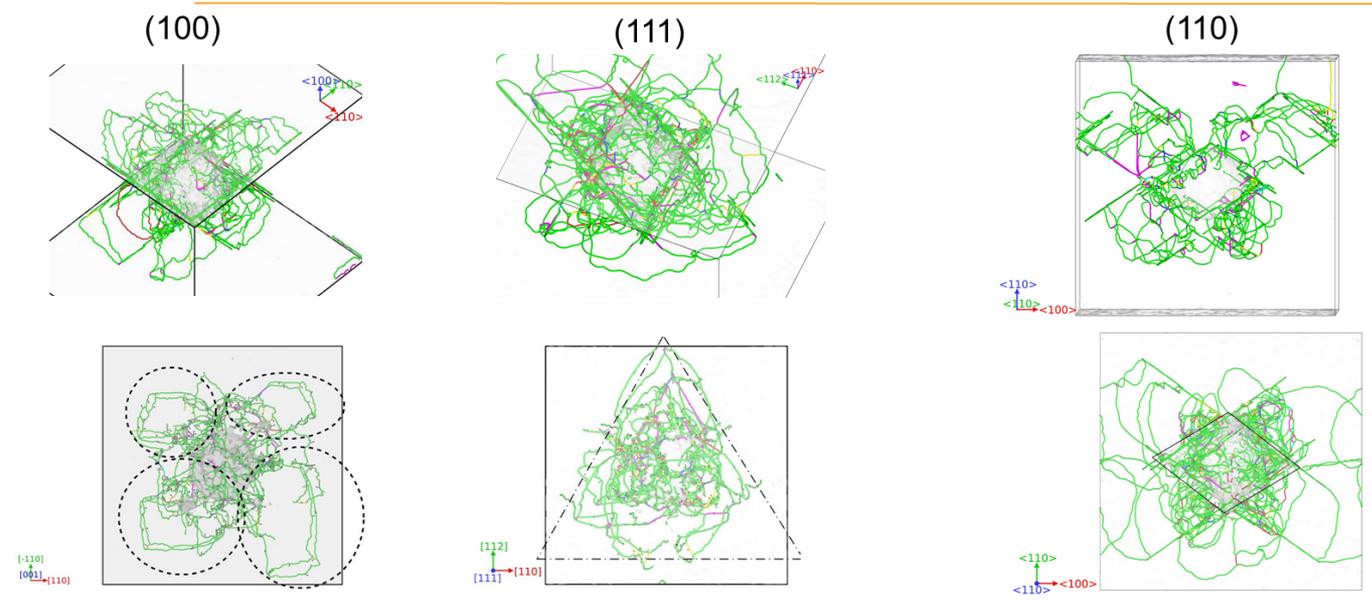




Surface protrusions with different crystallographic orientations



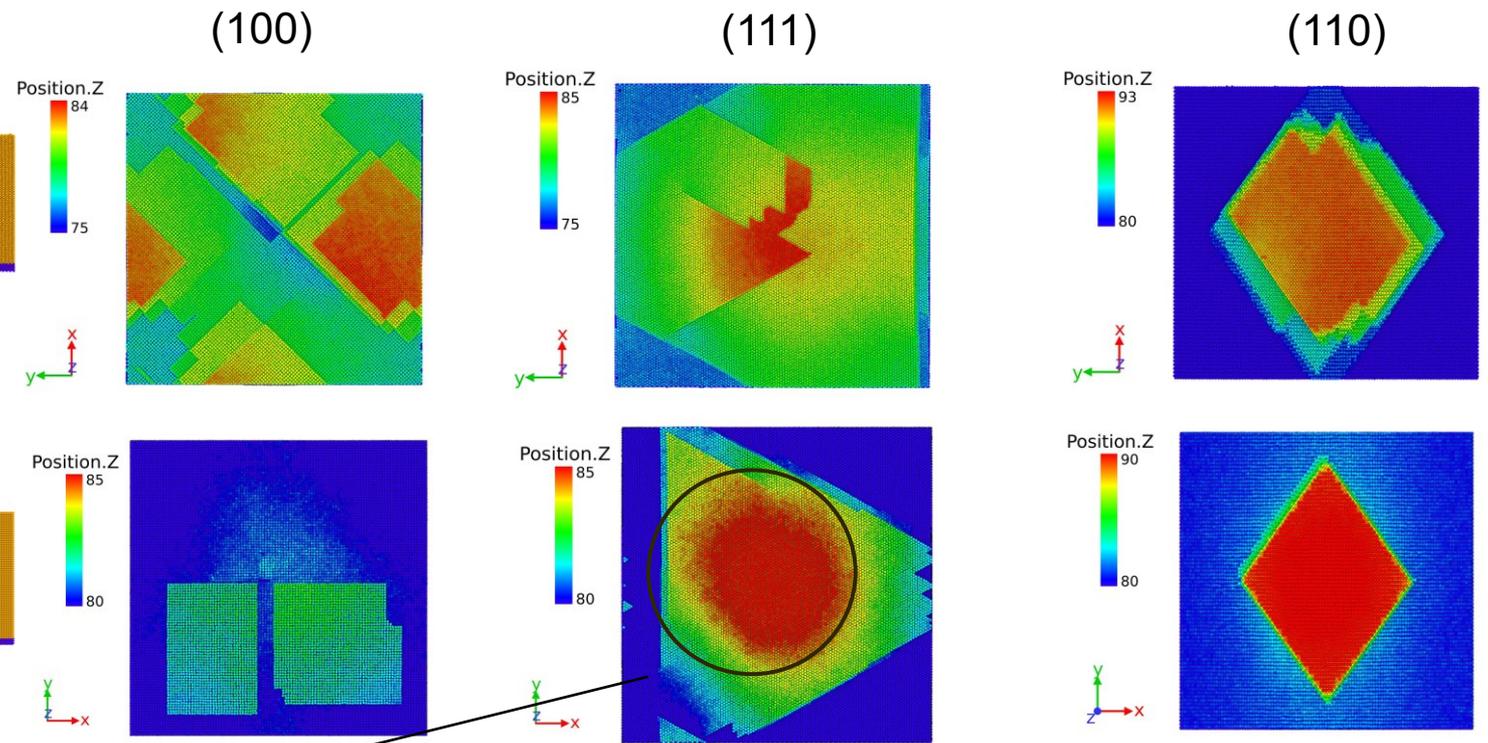
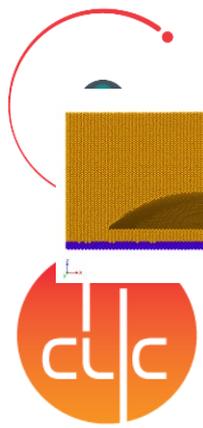
- In different directions we can see the formation of dislocation loops of a rhomboid shape in the $\langle 110 \rangle$ orientations.
- The dislocations travel in the slip planes, however the (100) surface attracts more dislocations than the (111), but less than the (110).
- The slip planes in FCC materials are the same, nevertheless, the interaction with the surface (or grain boundary) creates different features on surface



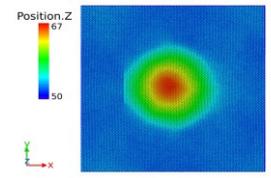
Green: Shockley partials. Blue: perfect partials. Red: "others" dislocations. Magenta: stair-rod. Yellow: Hirth. Cyan: Frank partial dislocations



Hemispherical and disk bubbles ($n_{H/Vac} = 2$)



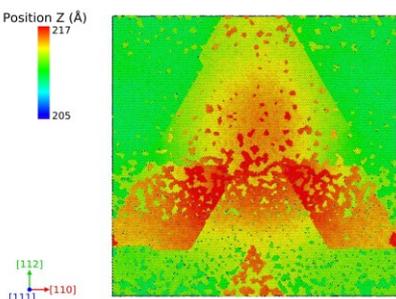
Circular shape at low H conc.



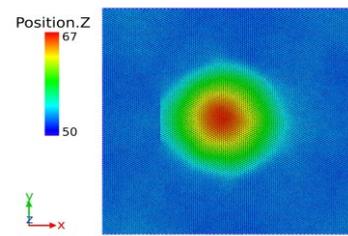
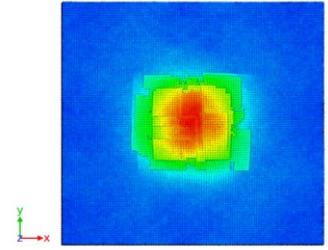
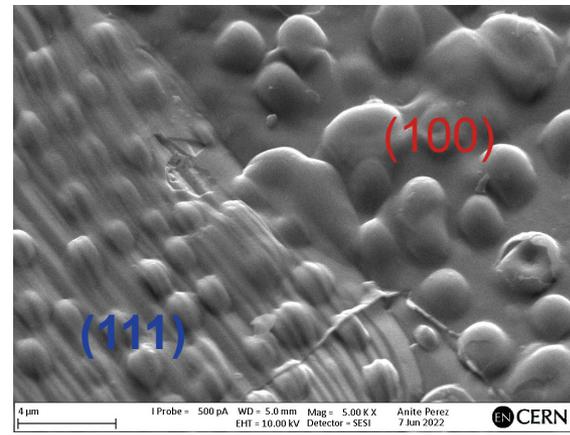
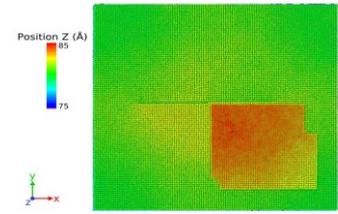
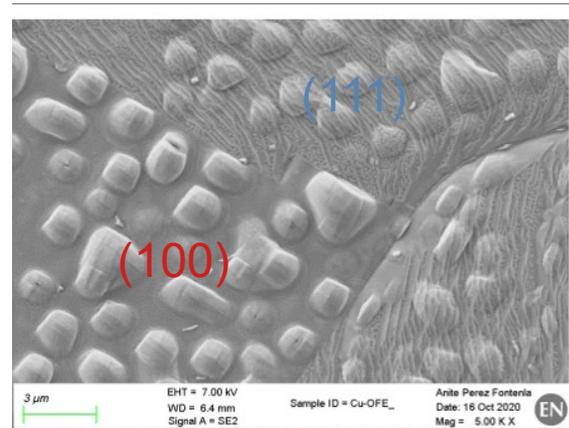
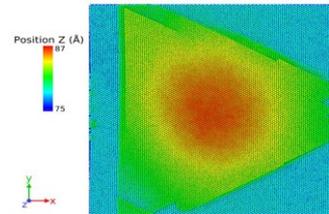
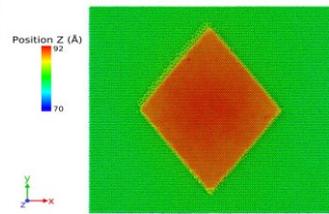
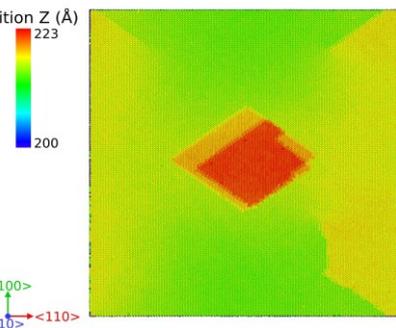
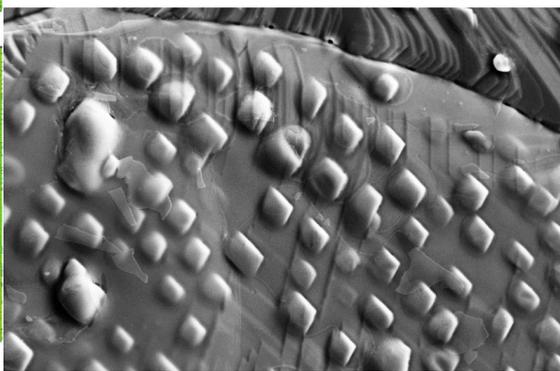
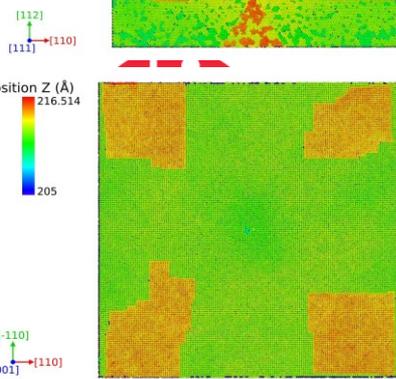
- Similar surface features as in the spherical void.
- However the disk-bubble generates clearer protrusions.



Comparison with experiments



(110)

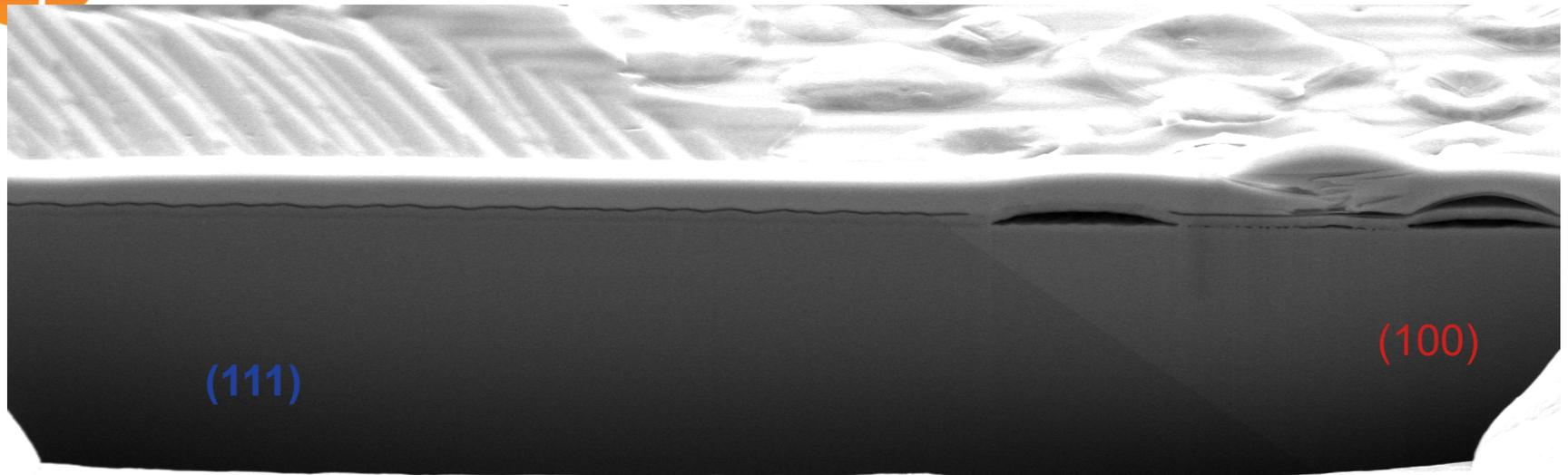


MDRANGE vs BCA

➤ The MD results do not provide information on why (110)/(111) are not the first surface yielding, being the glide direction/plane. We see (110) is the first yielding, contradicting the experiments.

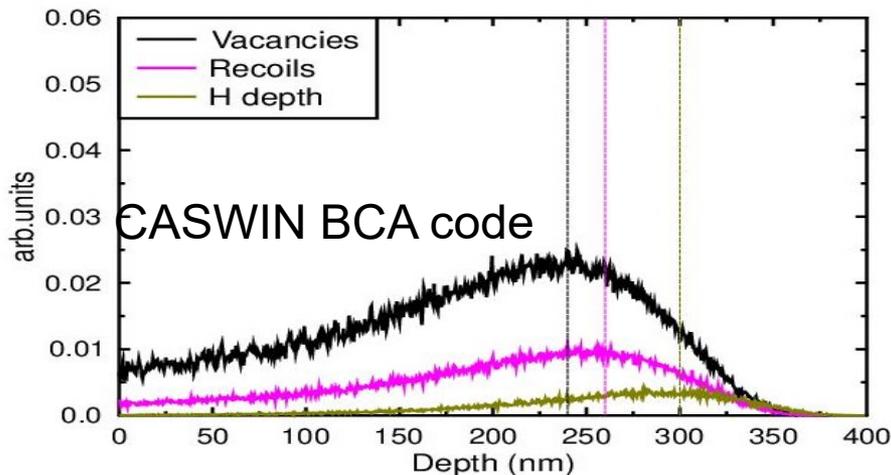
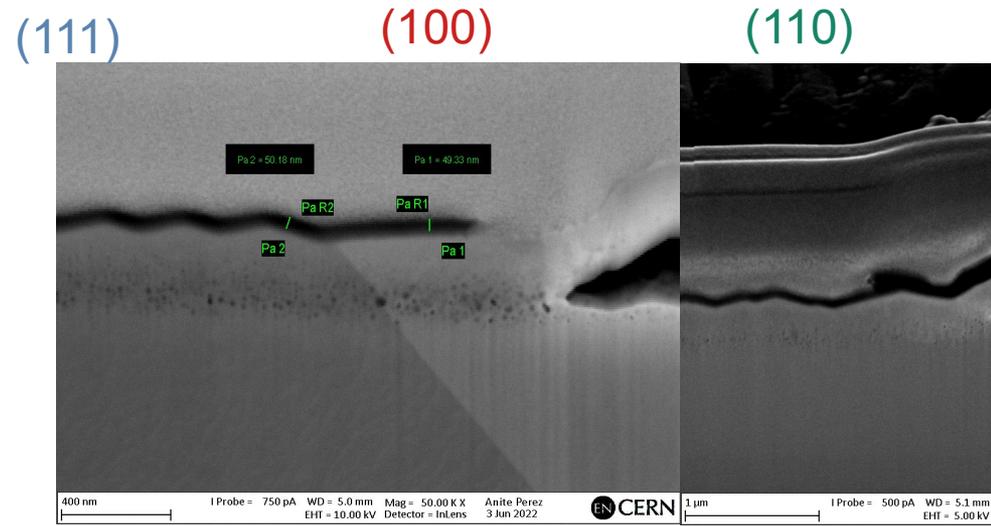
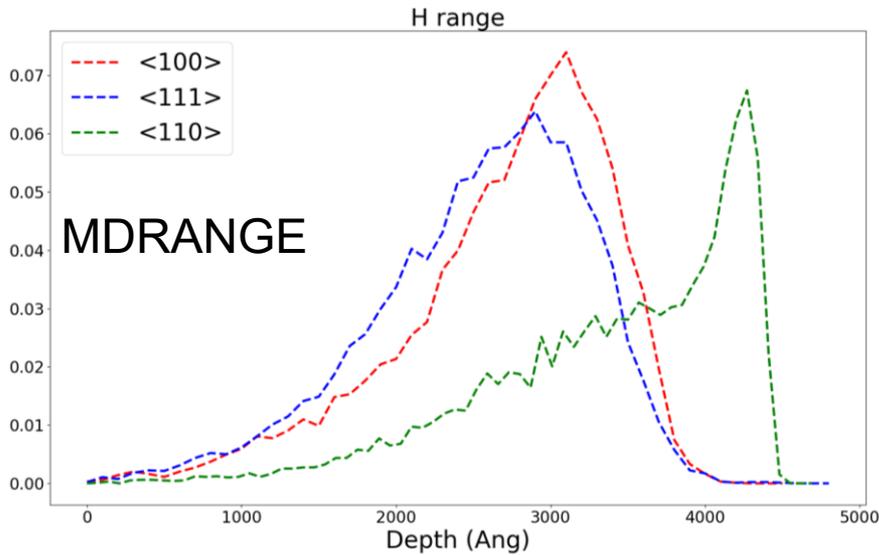
➤ Since the initiation sites are formed at different depths depending on the grain orientation, we need to know how the penetration depths are for 45 keV H in Cu. For that we use MDRANGE, when typically Monte Carlo methods are commonly applied to this problem.

➤ MDRANGE* is an MD approach specifically designed for high-energy interactions and allows for consideration of different crystallographic orientations.





MDRANGE vs BCA

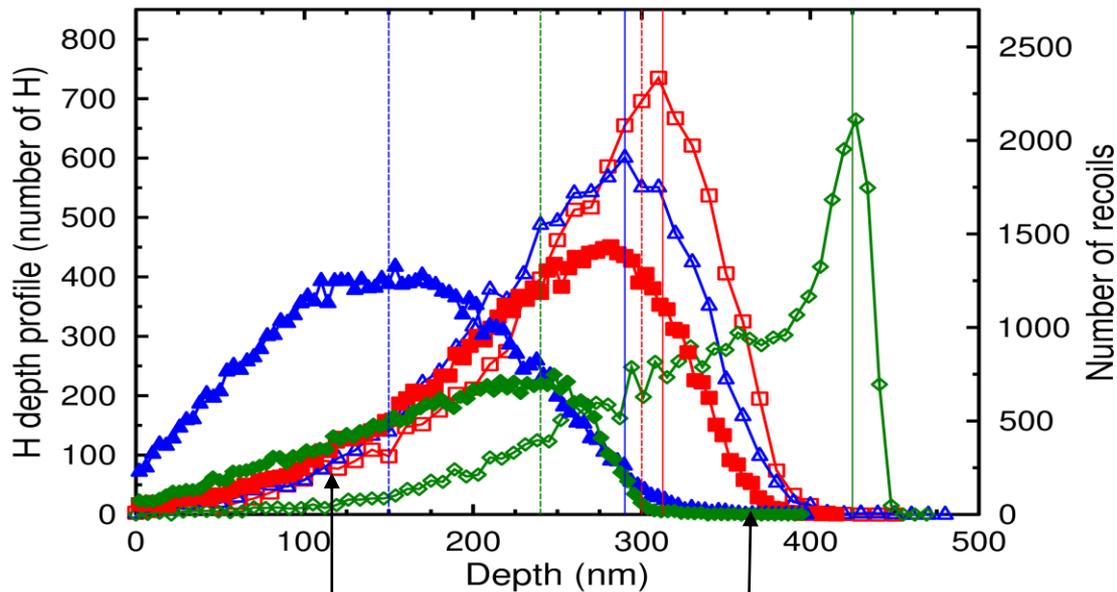
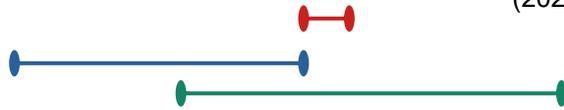


- The studied grains under low fluence show that bubbles are formed at different distances, which is consistent with MDRANGE results, observing a deeper formation in (110) grains.
- After a complete dataset of blisters/protrusions is obtained with MD, we understand the mechanisms of surface modification. However, we observe that under low fluences, only (100) grains experience blistering.

Comparison with experiments

➤ We filter those recoils with kinetic energy lower than 40 eV (approximately the energy needed to create a vacancy), and we observe that for $\langle 100 \rangle$ the peaks are close, however the distances between them in $\langle 111 \rangle$ and $\langle 110 \rangle$ (specially the latter)

A. Lopez-Cazalilla, C. Serafim, F. Djurabekova, Acta Materialia, 266, 119699 (2024)



H by open markers

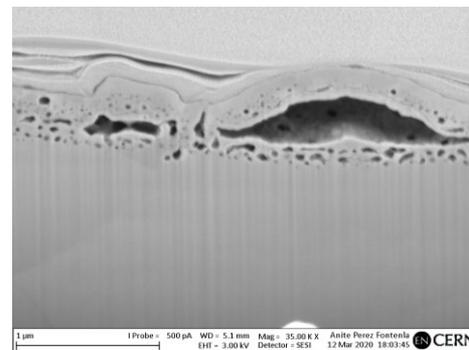
Vacancy by filled markers

➤ The formation of vacancies occurs closer to the surface in $\langle 111 \rangle$ and $\langle 110 \rangle$ grains, but the hydrogen atoms need more time (fluence) to fill these gaps and develop larger blisters visible in the surface, while in $\langle 100 \rangle$ is immediate



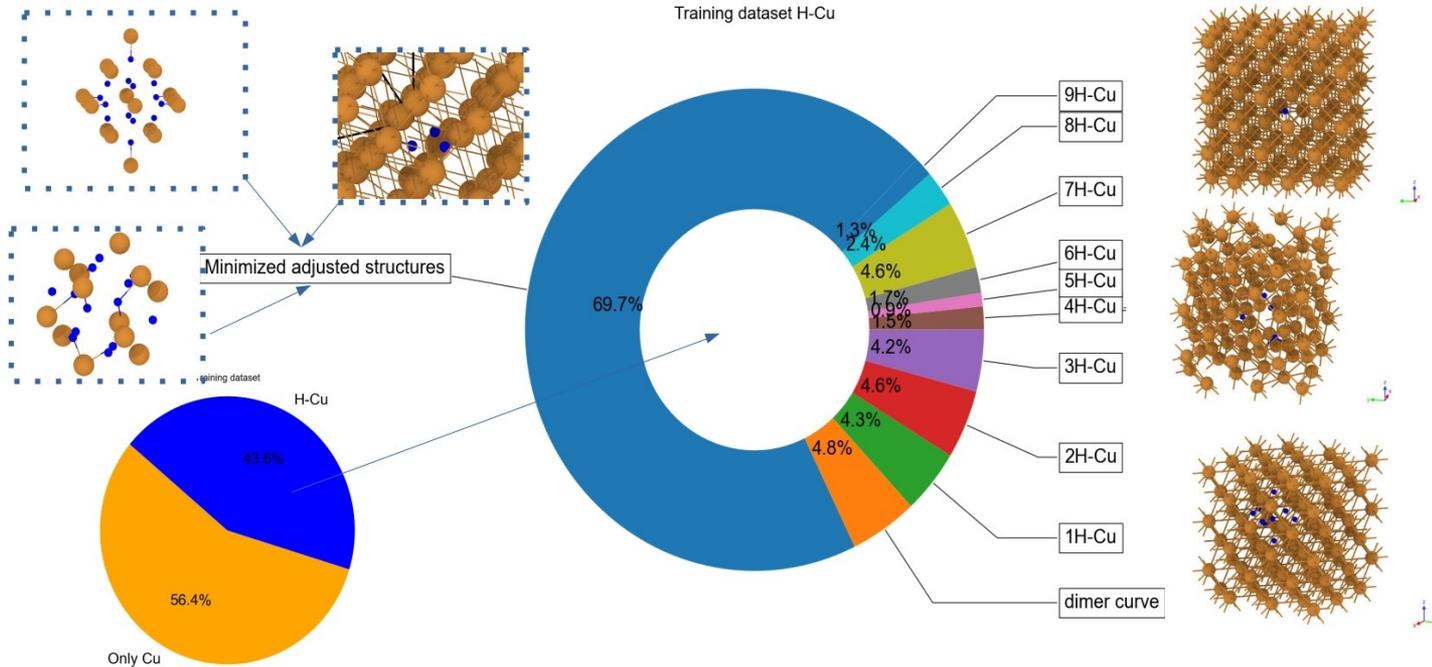
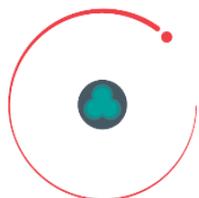
Cu-H Machine-learned interatomic potential

- The process of **bubble coalescence** and **the interaction of H with dislocations formed during the growth of bubbles (intermediate stage)** remain inaccessible by our current model. The application of purely repulsive interaction between H and Cu is limited.
- The development of a potential that can reproduce the processes that occur in the first stages of the bubble growth is needed.
- Only one interatomic potential (besides purely repulsive) is currently available for H-Cu interaction. However, the interaction between H and Cu is highly attractive, showing unrealistic results for bubble growth⁽³⁾.
- We choose the machine learning approach to design a new potential with the inputs from density functional theory calculations





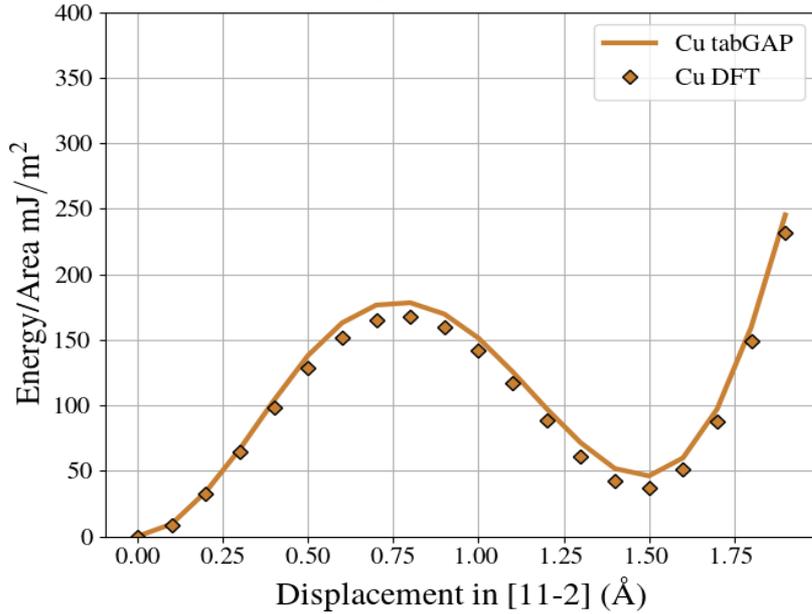
Cu-H MLIP. Training dataset



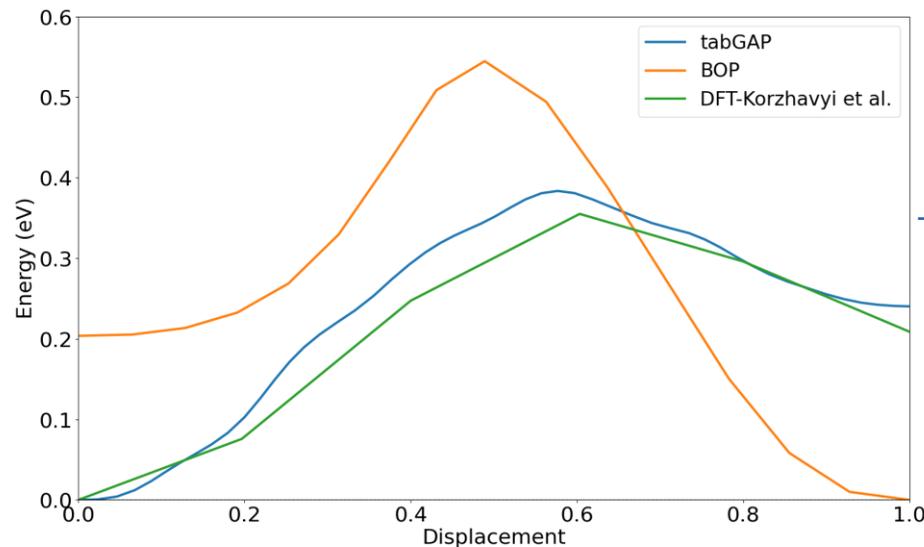


Cu-H MLIP. Performance tests

Courtesy of Aslak Fellman

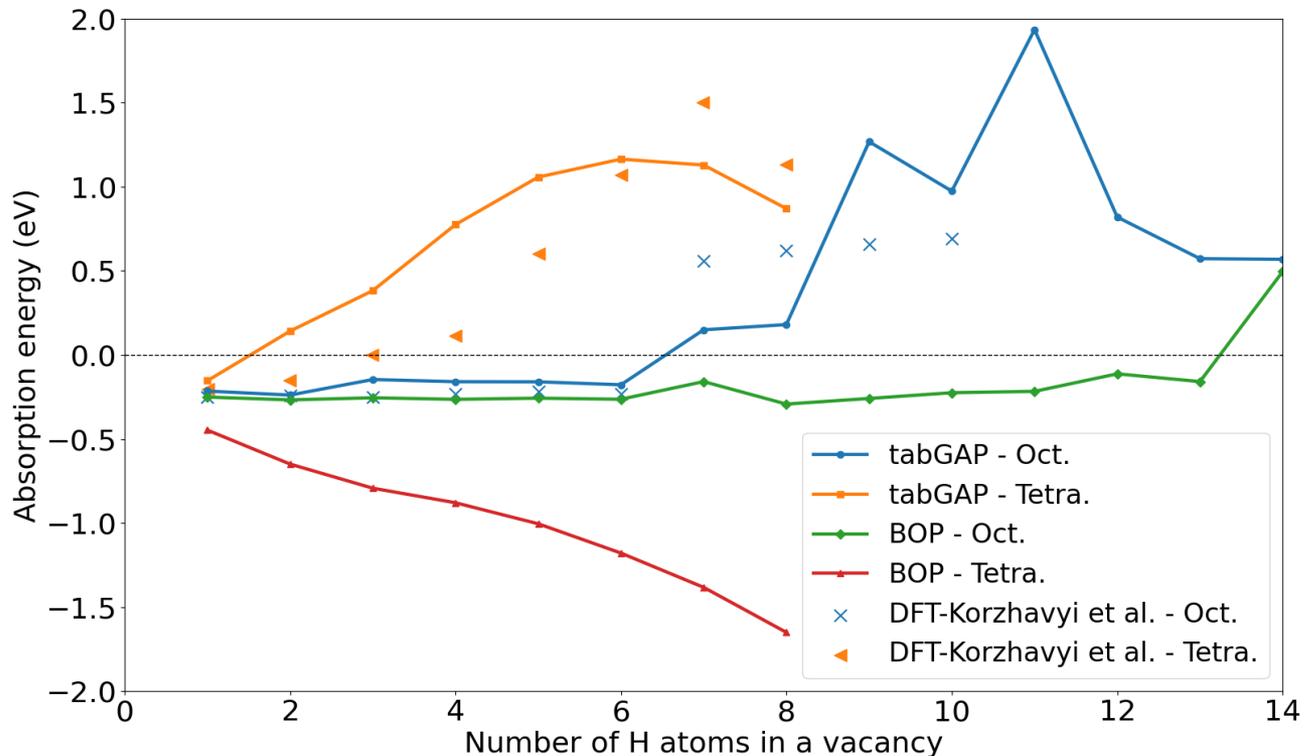


The insertion of the H dataset did not modify the mechanical properties of the copper part



The barrier of a H atom moving from an octahedral to a tetrahedral position is predicted close to DFT precision. And better than the other available potential (BOP)

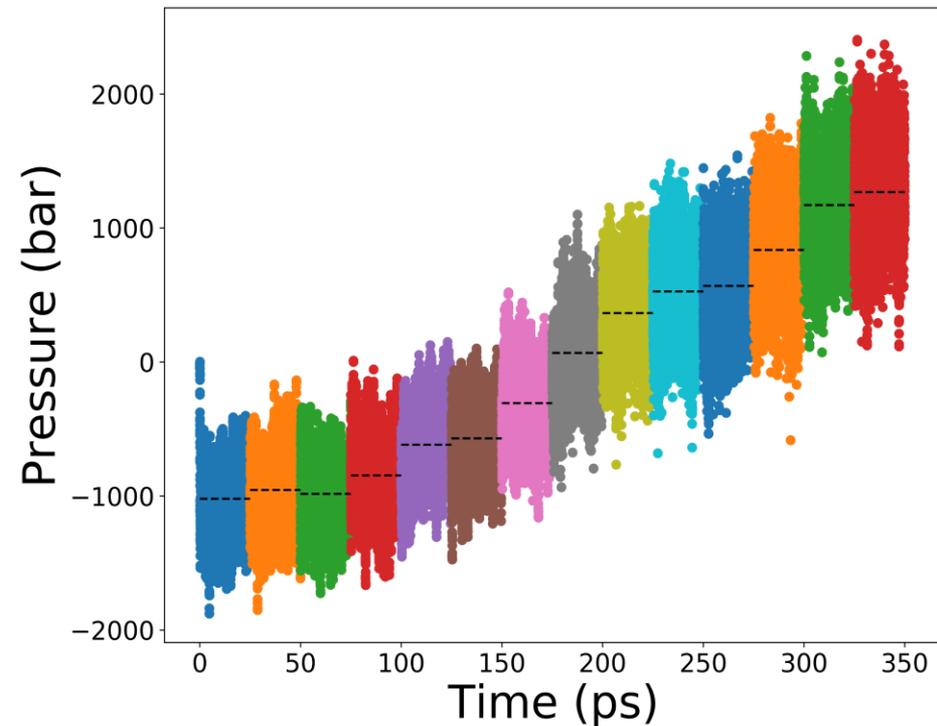
Cu-H MLIP. Performance tests



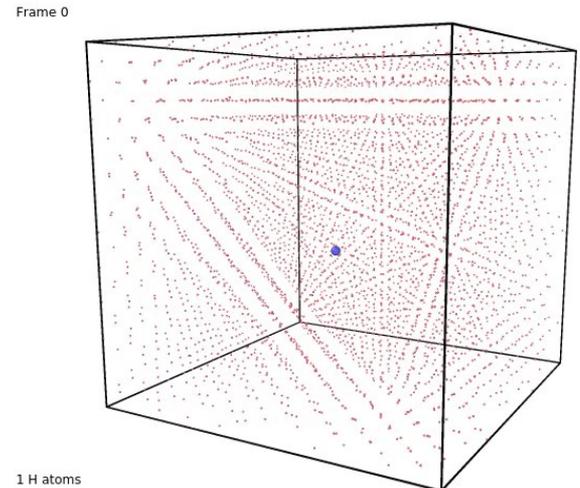
- Comparing with BOP, tabGAP predicts an absorption energy closer to DFT, with similar trend.
- DFT predicts that no more than 6 H can be accommodated in 1 vacancy



Cu-H MLIP. Sequential insertion of H



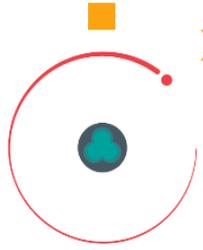
- $N_H = 1$
- $N_H = 2$
- $N_H = 3$
- $N_H = 4$
- $N_H = 5$
- $N_H = 6$
- $N_H = 7$
- $N_H = 8$
- $N_H = 9$
- $N_H = 10$
- $N_H = 11$
- $N_H = 12$
- $N_H = 13$
- $N_H = 14$



- This potential allows to follow processes such as the accumulation of H in small defects such as small vacancy clusters, and assists on what experimentally is not possible to follow.



Conclusions

- 
- In our simulations we clearly see the atomistic mechanisms of bubble and blister growth under hydrostatic internal H pressure. We identify the effect of surface orientation on the shape of appearing protrusion.
- 
- The observed differences in the protrusion shapes with MD are consistent with those seen in experiment
 - The difference between the formation of vacancies area and the penetration depth of H in (110) and (111) grains explain the later development of blisters, complementing the penetration depth as previous models predicted.
 - The ML potential, with DFT precision, enables the exploration of mechanisms behind the blistering effect.



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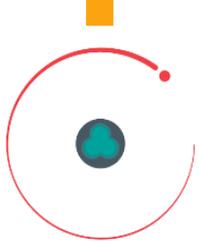
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(²) Internal communication with CERN for Titanium not-blistering

(³) Zhou, X.W., Ward, D.K., Foster, M. et al. An analytical bond-order potential for the copper–hydrogen binary system. J Mater Sci 50, 2859–2875 (2015)

(⁴) J. Byggmästar, K. Nordlund, and F. Djurabekova, Simple machine-learned interatomic potentials for complex alloys, Phys. Rev. Materials 6, 083801 (2022)



Thank you for you attention!